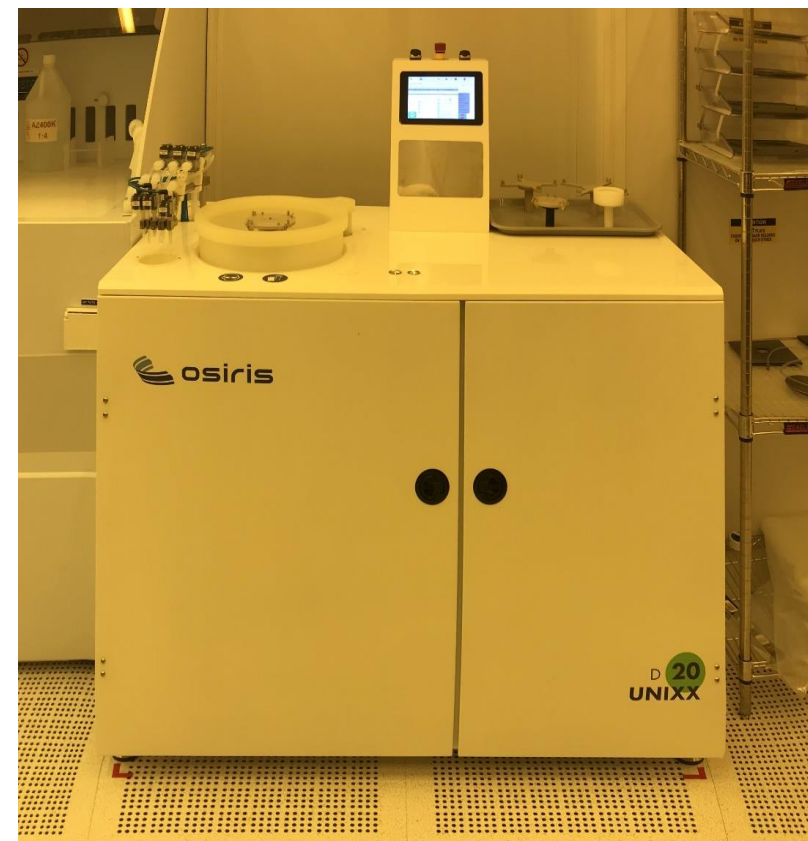


Automated Wet Chemical Processing@



100 μ m



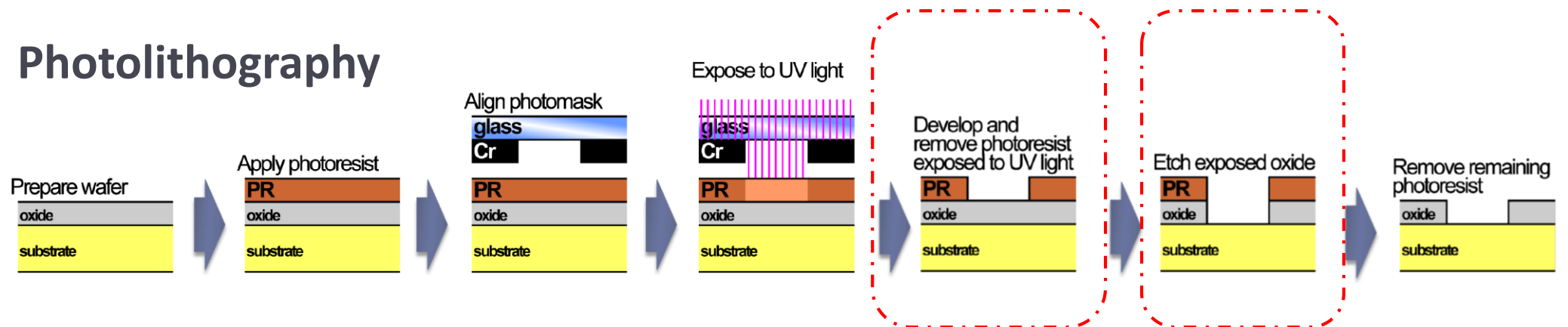
By Shaoning Lu and Serkan Butun



In this talk...

- Typical wet processes used in NUFAB
- What new automation tools NUFAB offers for wet processing?
 - Developing
 - Photomask Etching

Photolithography



Any process in which the substrate is in contact with a liquid chemical is considered wet process.

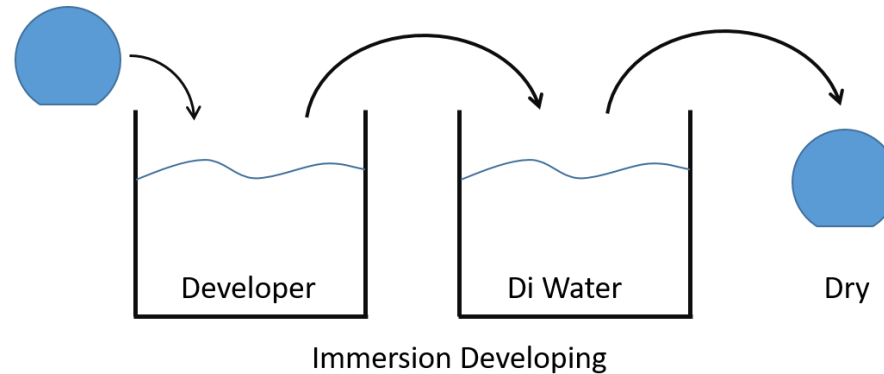
- **DI water rinsing**
- **Solvent cleaning** – Acetone, IPA, NMP
- **Photoresist Developing** – MIF, MIC, solvent developing
- **Acid etching** – Buffered oxide etching, photomask etching, HNO₃, Nanostrip
- **Alkaline etching** – KOH, TMAH

Developers at NUFAB

Developer	Type	Main ingredient	Normality	Surfactant
AZ400K 1:4	MIC	KOH	0.278	no
AZ300 MIF	MIF	TMAH	0.261	no
AZ971 MIF	MIF	TMAH	0.261	yes
MF 319	MIF	TMAH	0.237	yes
SU8 Developer	solvent	PGMEA	n/a	no



Typical developing process



Some tips..

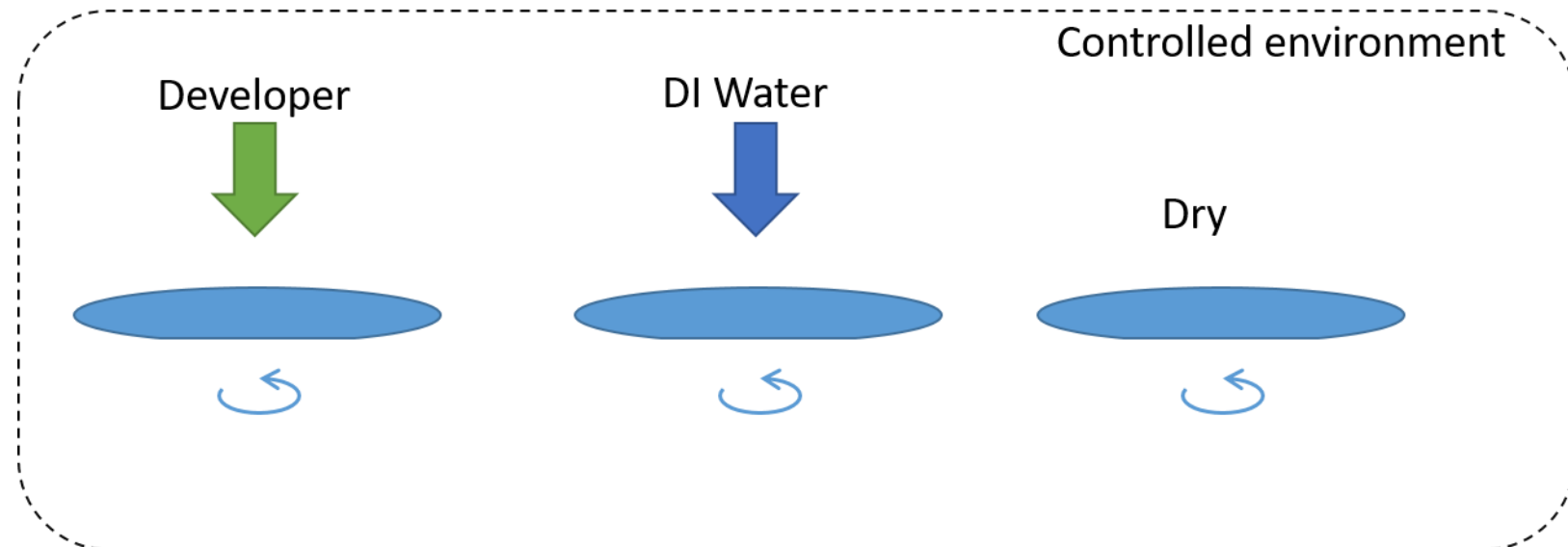
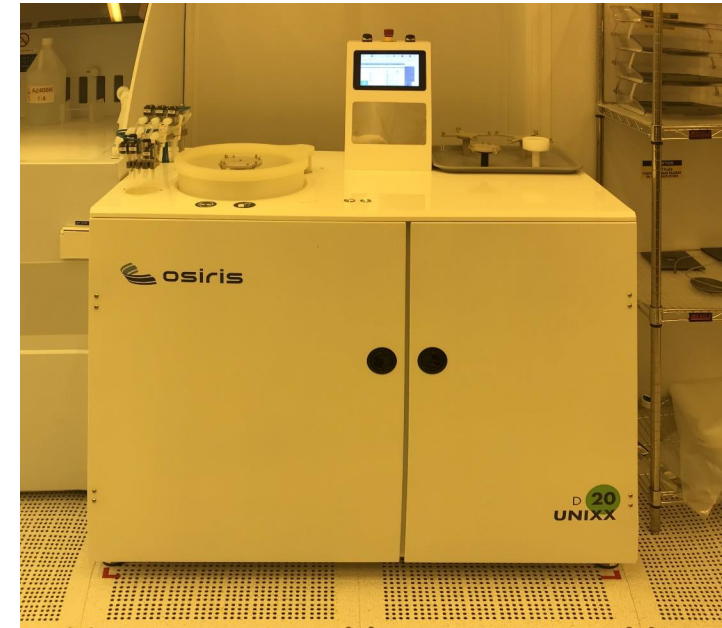
- Always clean labware well before usage. – Consider having your own labware for critical processes.
- **Rinse well after develop – rule of thumb: rinse at least as long as your develop time.**
- Never let chemicals dry on your substrate – use N2 gun
- **Know when to agitate**
- There are advanced methods for high aspect ratio patterning – cold developing, hypersonic assist, upside down developing ...
- **Ask for help, we are here for you!**

Problems $_ (\text{ツ}) _ /$

- Sample handling
 - Dropping sample, scratches, over-developing
- Unclean labware
 - Impurities alter the developing time even at ppb levels
- Safety
 - Contact with Hazardous chemicals
- Cost of materials/disposal
 - Environmental impact

Introducing puddle developing

- Automated process
- Precise control
- Minimal user input
- Dry in / dry out
- Less developer/waste

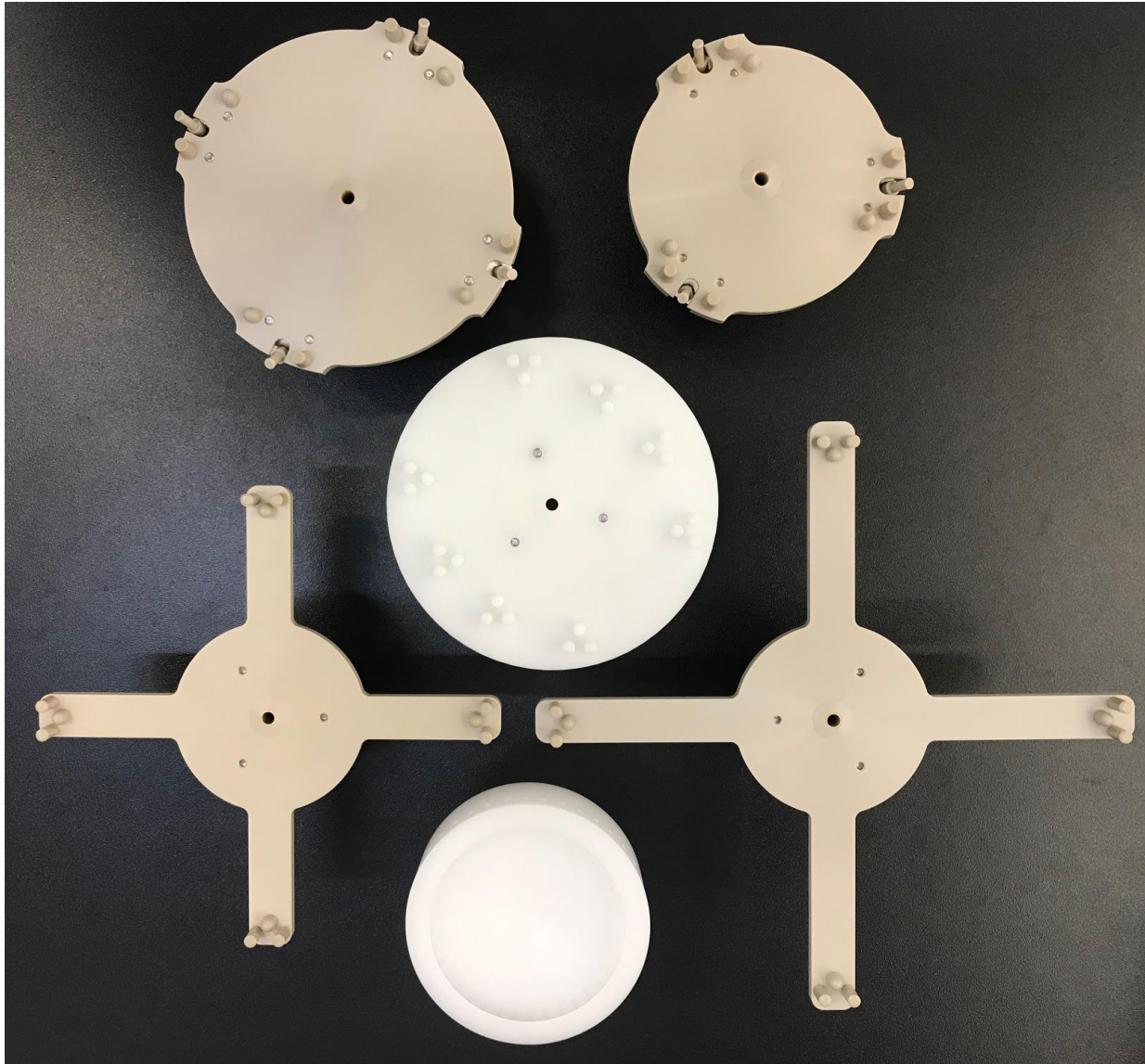


Available chemicals and recipes

- AZ400K 1:4
- SU8 Developer
- IPA
- DI Water
- S1805
- S1813, AZ5214E*
- AZP4620
- SU8 2002
- SU8 3010
- Sample rinse
- Sample dry

We are actively developing new recipes, let us know if you need a particular one..

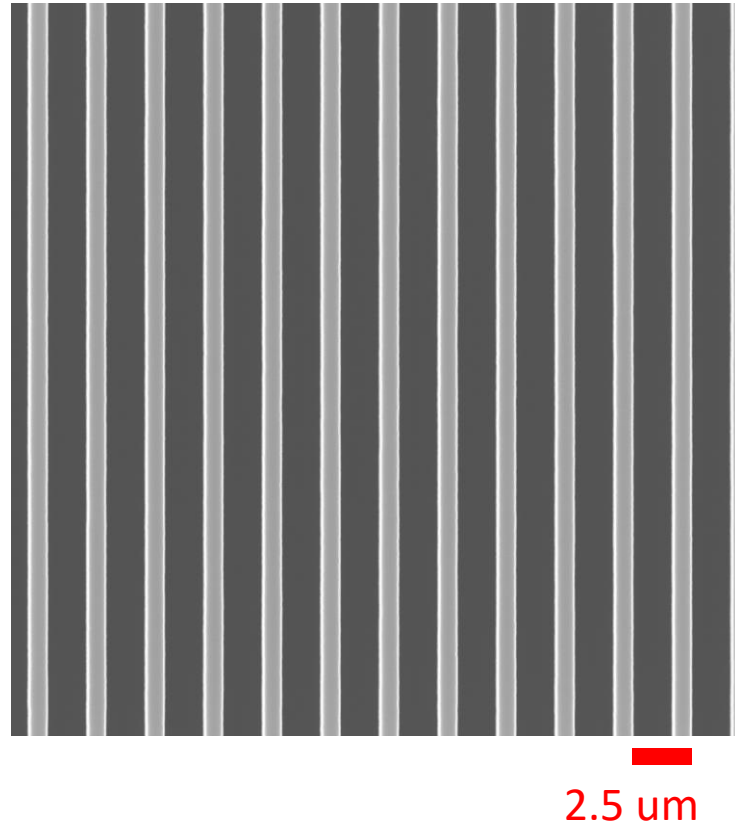
Substrate Chucks



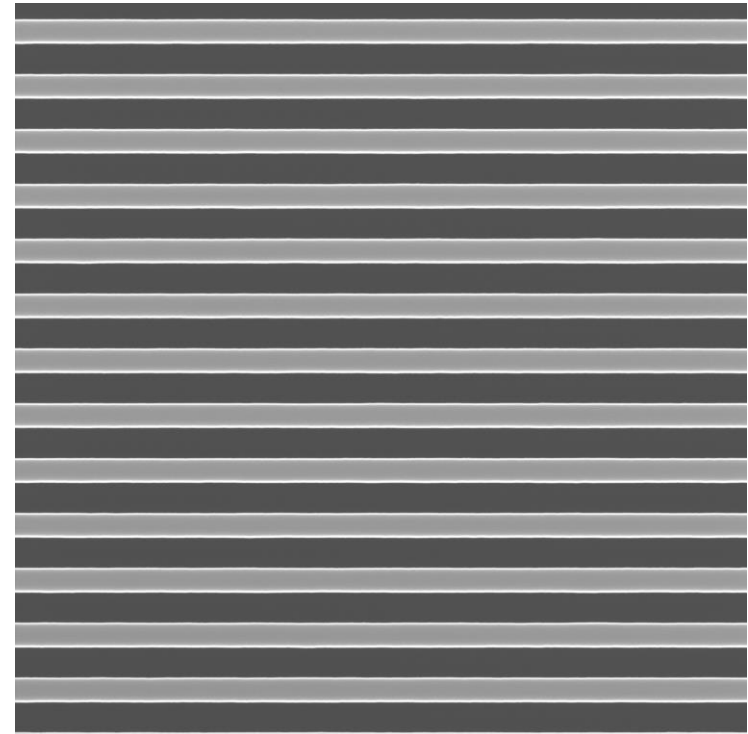
- 3 inch wafer
- 4 inch wafer
- 4 inch mask
- 5 inch mask
- 1by3 microscope slide
- 2by3 microscope slide
- Small piece basket

It is possible to get chucks for any shape substrate

High resolution process examples



3 um



This sample is exposed in Heidelberg MLA150, **developed in Osiris Automatic Developer** and etched in STS DRIE.

Demo video

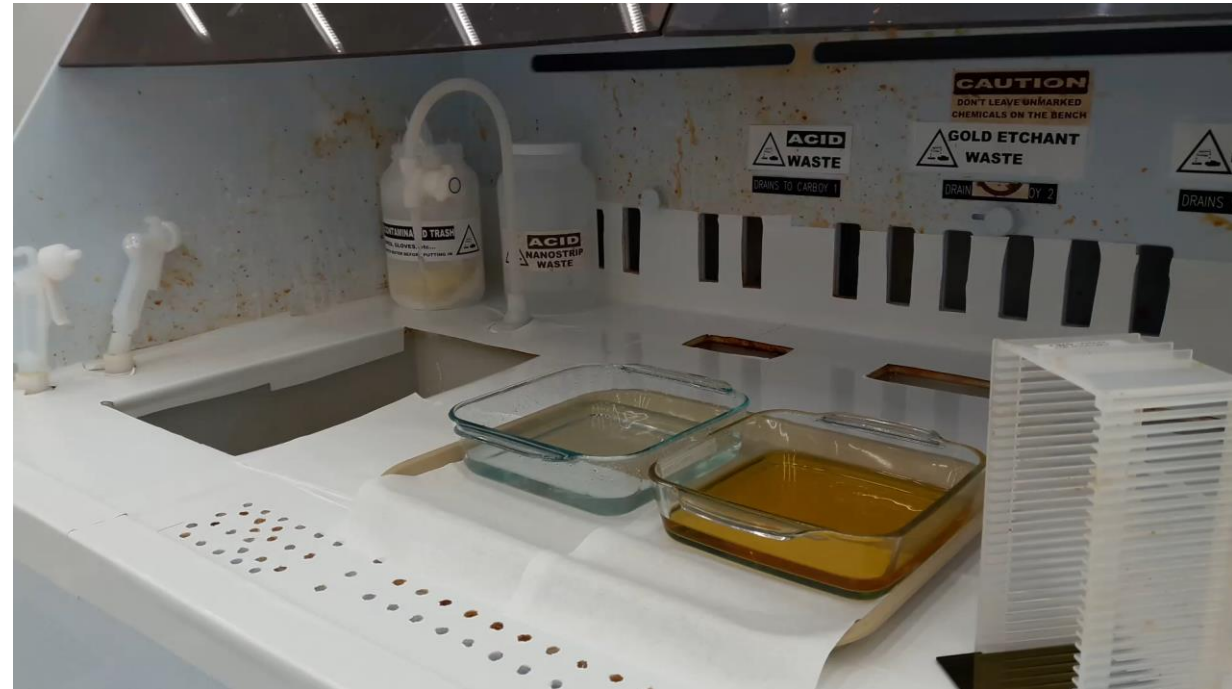
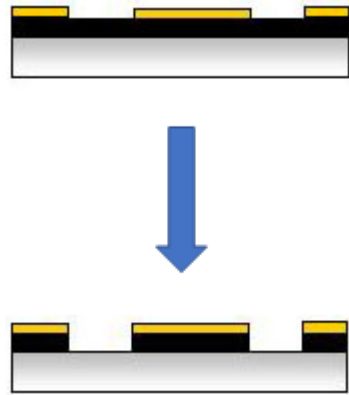


Osiris Automatic Acid Station

- Dry-in dry-out process
- Highly controlled process
- Much safer and much less cleaning work for users
- Lots of time saving for photomask and many other pattern etching
- Expandable in the future for more chemicals



This is how we etch a photomask manually

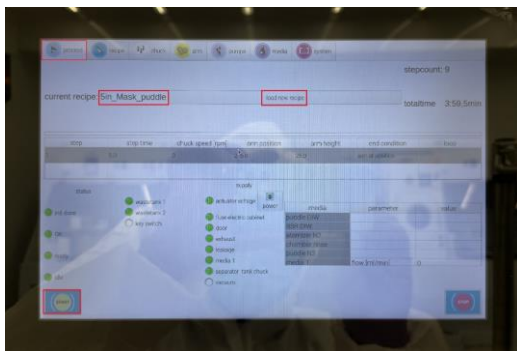
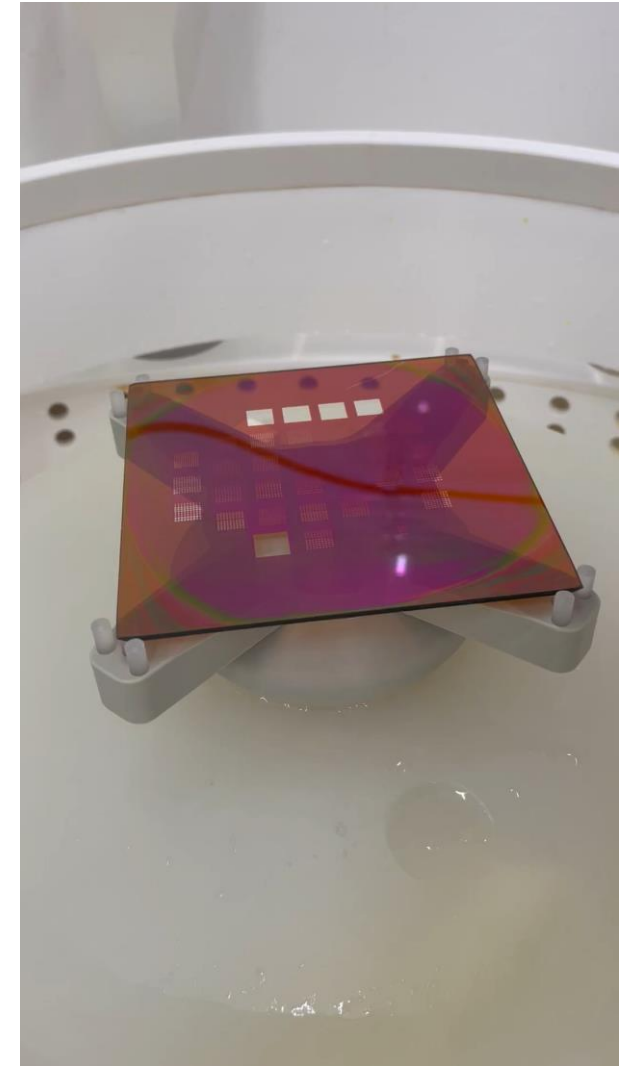
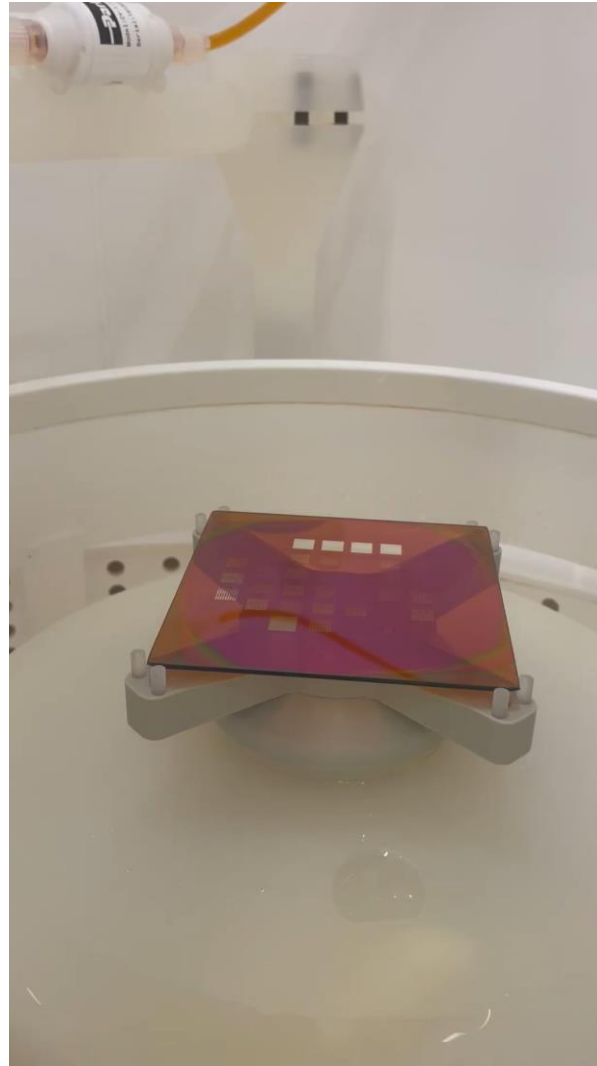


Acid that we're dealing with

- HNO_3
- HCl
- HClO_4
- H_2SO_4
- HF
- H_3PO_4

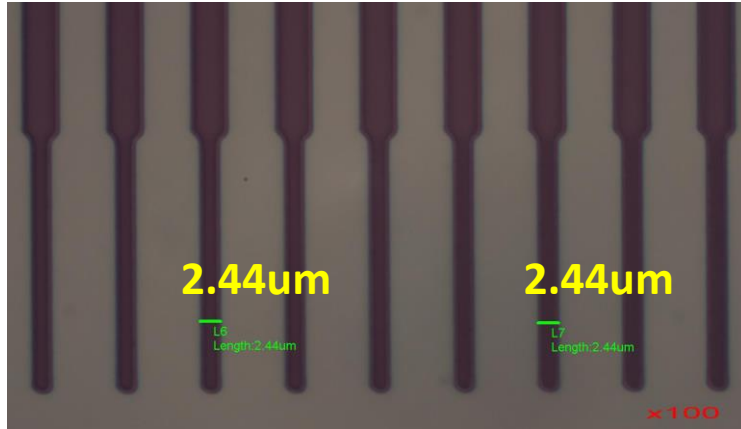


With Automatic Iron Oxide Etch

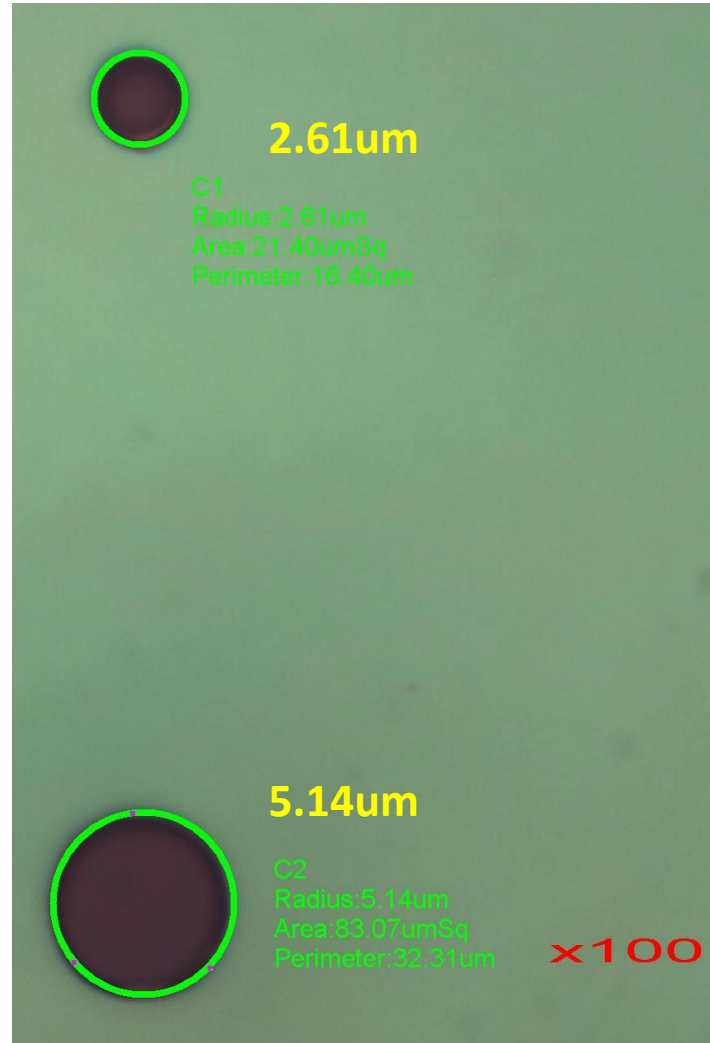


Etch Result

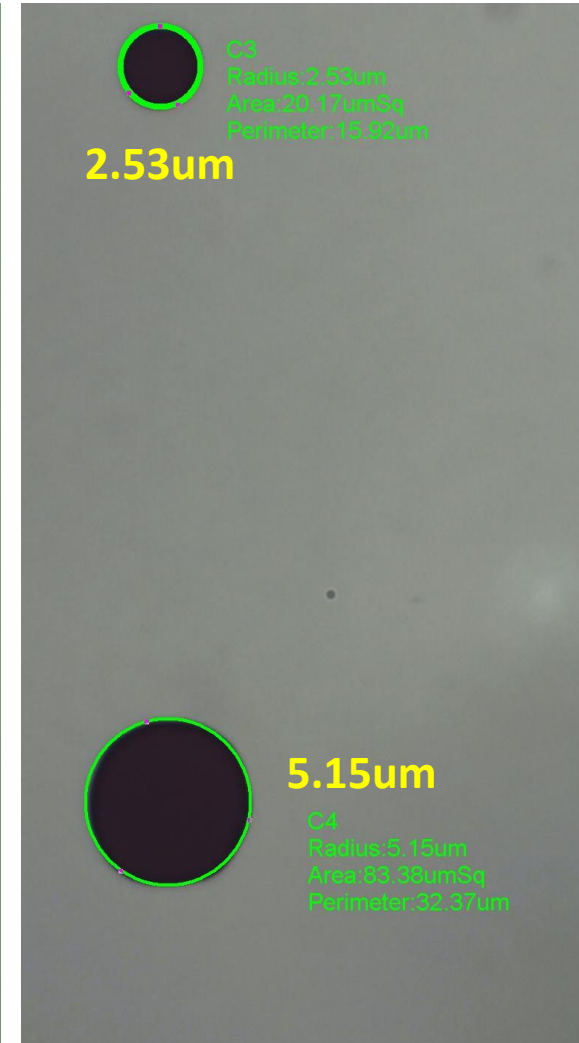
With PR



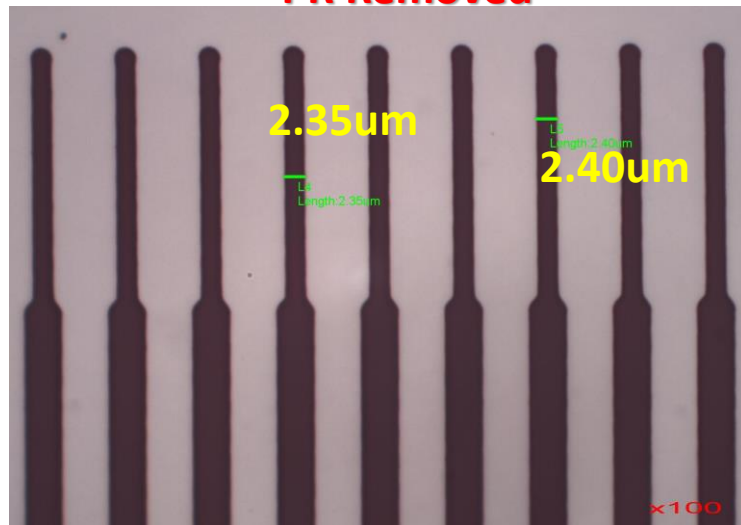
With PR



PR Removed

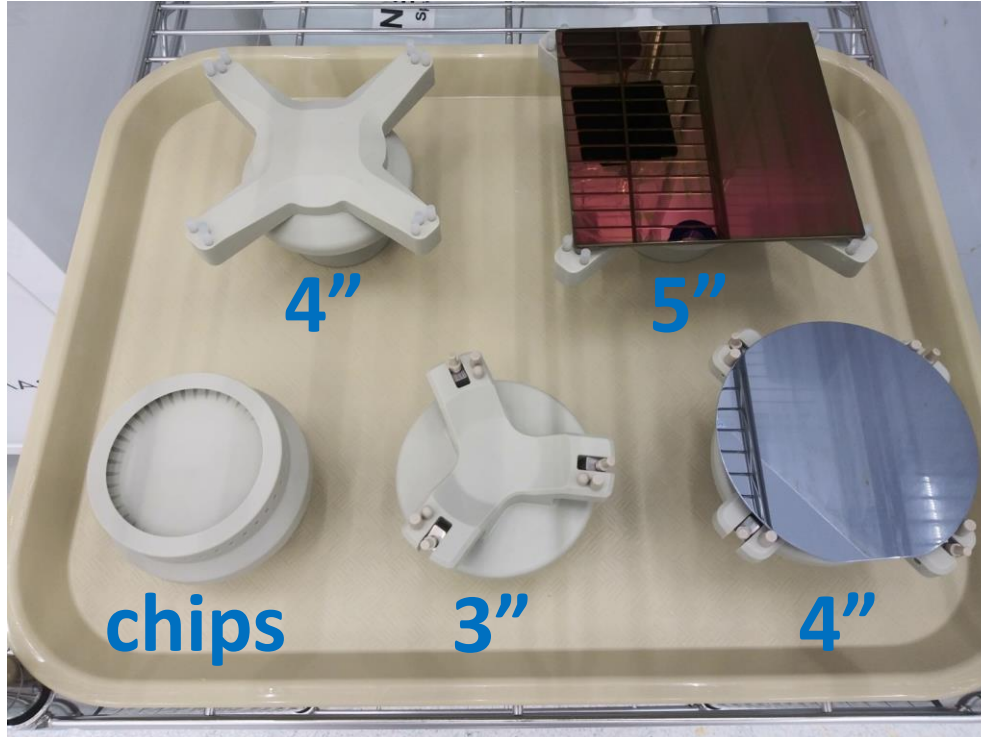


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What is the next chemical to add?

- 5 choices of sample size
- 3 more space for chemicals



Recap: current wet and dry etch capabilities in NUFAB

□ Wet Etch

- Cr
- FeO
- Cu
- Au
- Al
- Ni
- Ti
- SiO₂
- Pt/Mo
- PR/Other organics

□ Dry Etch

- Si
- SiO₂
- SiN
- Polymers

Finally..

- We are working hard to serve micro/nano fabrication in research.
- Which chemicals are you (will you be) interested in using in the automatic developer/etcher systems?
- Please feel free to contact staff for your application questions or process development.

Thank you!

Questions?